



Material Content Data Sheet



Sales Product Name		TLE42994GM V33		Issued		22. January 2018		
MA#		MA001396144						
Package		PG-DSO-14-30		Weight*		143.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	2.09	2.09	20926	20926
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8432	
wire	non noble metal	copper	7440-50-8	49.007	34.24	35.13	342359	351318
	noble metal	gold	7440-57-5	0.203	0.14	0.14	1421	1421
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1201
plastics		epoxy resin	-	7.910	5.53		55260	
	inorganic material	silicondioxide	60676-86-0	77.898	54.42	60.07	544187	600648
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8566	8566
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7194	7194
glue	plastics	acrylic resin	-	0.313	0.22		2184	
	noble metal	silver	7440-22-4	1.108	0.77	0.99	7743	9927
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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